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EV GROUP HIGHLIGHTS TECHNOLOGY FIRSTS, KEY ADVANCEMENTS AT SEMICON WEST 2011

Recent Developments Span 450-mm Wafer Bonding, In-Line Metrology, Growth in Target Markets, Headquarters Expansion, and Industry and University Collaborative R&D Efforts

SEMICON WEST, San Francisco, July 12, 2011 – EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced it will showcase a number of recent corporate and technology developments at SEMICON West 2011, being held this week at San Francisco's Moscone Convention Center. The company has seen an increase in order intake in fiscal 2011 of approximately 40 percent compared with fiscal 2010, and will break ground this month on an expansion that will more than double its manufacturing floor space. EVG credits these successes to its ongoing focus on development and innovation within its target markets.

Industry-first capabilities point to innovation

The most recent breakthrough was the announcement yesterday of the EVG850SOI/450mm – the first-ever wafer bonding system for 450-mm-diameter semiconductor wafers manufactured from silicon-on-insulator (SOI) substrates. The new system, arising out of EVG's advanced 450-mm program, was developed to facilitate the industry shift to 450-mm wafers from the current 300-mm standard, and is optimized for SOI because it delivers better power/performance for sub-22 nm CMOS and 3D technologies compared to similar-geometry bulk CMOS. In addition, the new EVG bonder can continue to accommodate 300-mm wafers during the transition period. SOI leader Soitec will receive shipment of the first system, providing testing and qualification to speed production readiness.

Another first for EVG was the addition of an in-line metrology capability for its EVG850TB and EVG850DB automated temporary bonding and debonding platforms. Integrating these technologies together helps ensure detection of a variety of process irregularities and defects during bonding/debonding – ultimately, helping to optimize customers' wafer-thinning and bonding processes, reduce tool downtime resulting from processing yield issues, and maximize product yields and investments. Adding in-line metrology to thin-wafer processing is particularly crucial in helping to enable the ramp-up of 3D IC and through-silicon via (TSV) manufacture from pilot to volume production.

Collaborations and consortia help drive advancements

As the aforementioned innovations illustrate, EVG continues to take a leading role in driving 3D market evolution. In addition to having recently added several new customers in this arena, the company last week announced its engagement with the Georgia Institute of Technology 3D Systems Packaging Research Center (GT PRC). Through its membership, EVG's state-of-the-art temporary bonding and debonding, chip-to-wafer bonding and lithography technology and associated product and process expertise will be incorporated into the PRC's Silicon and Glass Interposer Industry (SiGI) Consortium research program.

Another core technology focus for EVG is the MEMS arena. In late June, EVG announced that its Gemini fully automated wafer-bonding system will be installed at Quebec's MiQro Innovation Collaborative Centre (C2MI), a partnership between Université de Sherbrooke, Teledyne DALSA and IBM Canada. The Gemini system will be used to develop products that demonstrate advanced packaging of MEMS devices and full integration of CMOS and MEMS devices, with the end goal of successful transfer to high-volume manufacturing (HVM) scenarios.

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As a strong proponent of education and early development of next-generation technologists, EVG has undertaken a sponsorship of SEMI High Tech U, an industry-driven math and science-based career exploration program created by the non-profit SEMI Foundation to support education and career awareness in high-technology fields. Its support will enable EVG to impact SEMI High Tech U's curriculum (which is designed to help students "make the connection" between the classroom and the real world of high tech) by meeting and collaborating with higher-learning institutions.

Corporate growth supports recent developments
The recent greater-than-expected uptick in orders underscores customers' continued confidence in EVG's innovation, technology leadership, and product and service quality. It also serves to validate the need for the ongoing expansion of EVG headquarters. Set to break ground this month and be completed by year end, EVG will modernize and more than double the space of its manufacturing floor and improve logistical processes, while continuing to invest additional capacity for its machining center and new manufacturing technologies.

EVG will be exhibiting and presenting at SEMICON West. Markus Wimplinger, corporate technology development and IP director, will speak on "In-line IR metrology for high-volume temporary bonding applications" at the SEMATECH Workshop on 3D Interconnect Metrology, Wednesday, July 13.

Editors and analysts interested in learning more about the company and its recent developments are invited to visit EVG's booth #1131 (South Hall), or attend the company's happy hour event at the booth, which will run from 3:00-5:00 p.m. on Wednesday, July 13.

About EV Group
EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple i-approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.EVGroup.com.

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